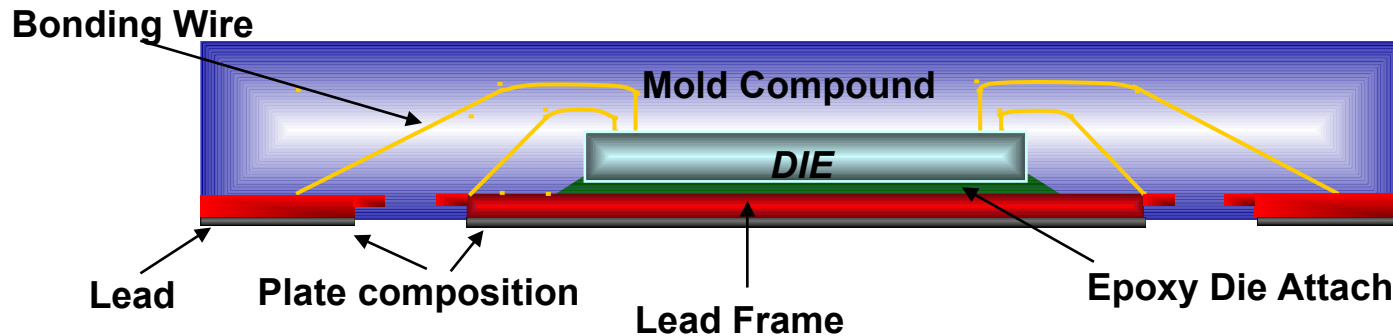


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Rev: 1.1

Cross-Section View VS1205G/VS1005G/VS8005G 88pin LFGA (ROHS)



SUBSTRATE (Lead Frame)

Plate composition

100% Sn

Plate thickness

300-800 micro inches

Material

Lead Frame

HDL (10X10) LF

Epoxy Die Attach

(VS1005 die) CRM1066C

Bonding Wire

COPPER 23 MICRONS

Mold Compound

EME G770HP